



| Product Description | | 3.3 V TO 5.0 V, 2.3 GHz TO 2.7 GHz LINEAR POWER AMPLIFIER – General Market Release | | |
|---------------------------------|--|---|---------------------------|-----------------------|
| Package Type | | QFN, 3x3x.45, 16 pin | Process Technology | RFMD InGaP HBT8 |
| Qualification # | | 08-QUAL-1112 | Date Issued: | 31-Aug-2009 |
| Test Name | | Test Standard and Conditions | Samples Per Lot | Test Results |
| P a c k a g e | Moisture Sensitivity Level 3x Cumulative Reflow | JEDEC J-STD-020 | 22 x 3 lots | Pass MSL 1, 260C |
| | Temperature Cycling Loose Piece | ESD22-A104 Condition G -55 /+125°C, soak mode 1,500 cycles, preconditioning per JESD22-A113 | 22 x 3 lots | Pass |
| | Solderability | JESD22-B102, 8 hr steam aging. Method 1 Dip/Look | 22 x 3 lots | Pass |
| D E V I C E | High Temperature Operating Life | JESD22-A108 125°C, RF bias, 1000 hours | 22 x 1 | Pass |
| | THB | JESD22-A101, 85°C, 85% RH non- condensing, 500 hours | 22 x 1 | Pass |
| | ESD HBM | JESD22-A114 | 3 x 1 lot | Pass 500V Class 1B |
| | ESD CDM | ESD22-C101C | 3 x 1 lot | Pass 750V Class C4 |
| Characterization | | RF5602-680 | 5x1 | Pass |
| Conclusion | | This product has passed all RFMD requirements for production release | | |